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Hu et al.

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(54) **3-D IC DEVICE WITH ENHANCED CONTACT AREA**

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Related U.S. Application Data

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H01L 23/535 (2006.01)

H01L 21/768 (2006.01)

H01L 27/115 (2006.01)

(Continued)

(52) **U.S. Cl.**

CPC **H01L 23/535** (2013.01); **H01L 21/768** (2013.01); **H01L 21/76838** (2013.01); **H01L 21/76883** (2013.01); **H01L 27/11548** (2013.01); **H01L 27/11575** (2013.01); **H01L 27/11582** (2013.01); **H01L 23/485** (2013.01);

(Continued)

(58) **Field of Classification Search**

CPC ... H01L 29/788; H01L 23/522; H01L 23/485;
H01L 29/41766

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

8,237,211 B2 8/2012 Fukuzumi et al.
8,981,567 B2 3/2015 Hu et al.

(Continued)

OTHER PUBLICATIONS

Kim, Jiyoung et al; Novel 3-D Structure for Ultra High Density Flash Memory with VRAT (Vertical-Recess-Array-Transistor) and PIPE (Planarized Integration on the same PlanE); 2008 Symposium on VLSI Technology Digest of Technical Papers; pp. 122-123. (cited in parent).

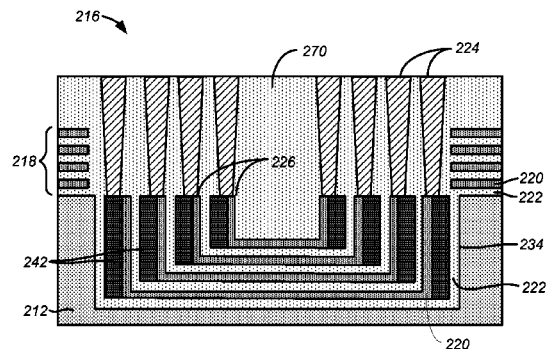
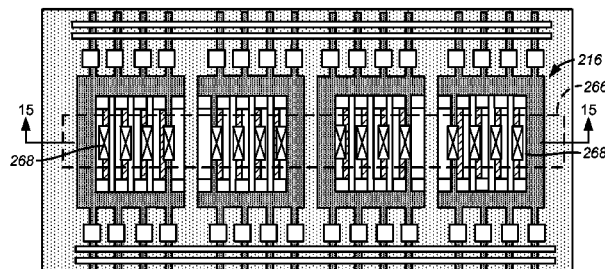
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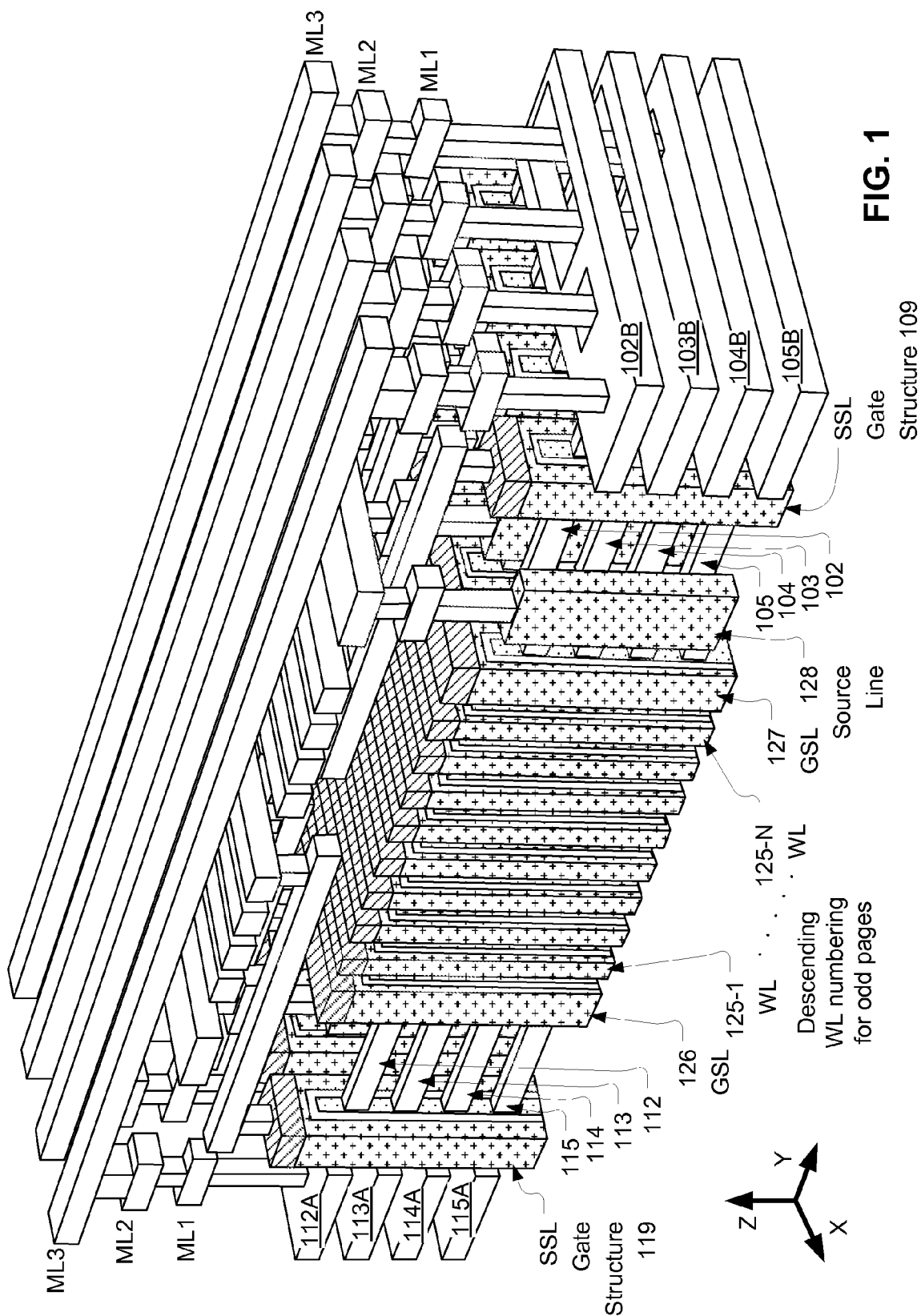
(57) **ABSTRACT**

A device includes a substrate with a recess, having a bottom and sides, extending into the substrate from the substrate's upper surface. The sides include first and second sides oriented transversely to one another. A stack of alternating active and insulating layers overlie the substrate's surface and the recess. At least some of the active layers have an upper and lower portions extending along upper and lower planes over and generally parallel to the upper surface and to the bottom, respectively. The active layers have first and second upward extensions positioned along the first and second sides to extend from the lower portions of their respective active layers. Conductive strips adjoin the second upward extensions of the said active layers. The conductive strips can comprise sidewall spacers on the sides of the second upward extensions, the conductive strips connected to overlying conductors by interlayer conductors.

22 Claims, 11 Drawing Sheets



(51)	Int. Cl.	(56)	References Cited		
	<i>H01L 23/522</i> (2006.01)		U.S. PATENT DOCUMENTS		
	<i>H01L 29/417</i> (2006.01)				
	<i>H01L 29/788</i> (2006.01)		2008/0099819 A1	5/2008	Kito et al.
	<i>H01L 23/485</i> (2006.01)		2008/0253183 A1	10/2008	Mizukami et al.
(52)	U.S. Cl.		2009/0001419 A1	1/2009	Han et al.
	CPC <i>H01L 23/522</i> (2013.01); <i>H01L 27/11556</i>		2010/0254191 A1	10/2010	Son et al.
	(2013.01); <i>H01L 29/41766</i> (2013.01); <i>H01L</i>		2012/0182806 A1	7/2012	Chen et al.
	29/788 (2013.01); <i>H01L 2924/0002</i> (2013.01)		2012/0182808 A1	7/2012	Lue et al.



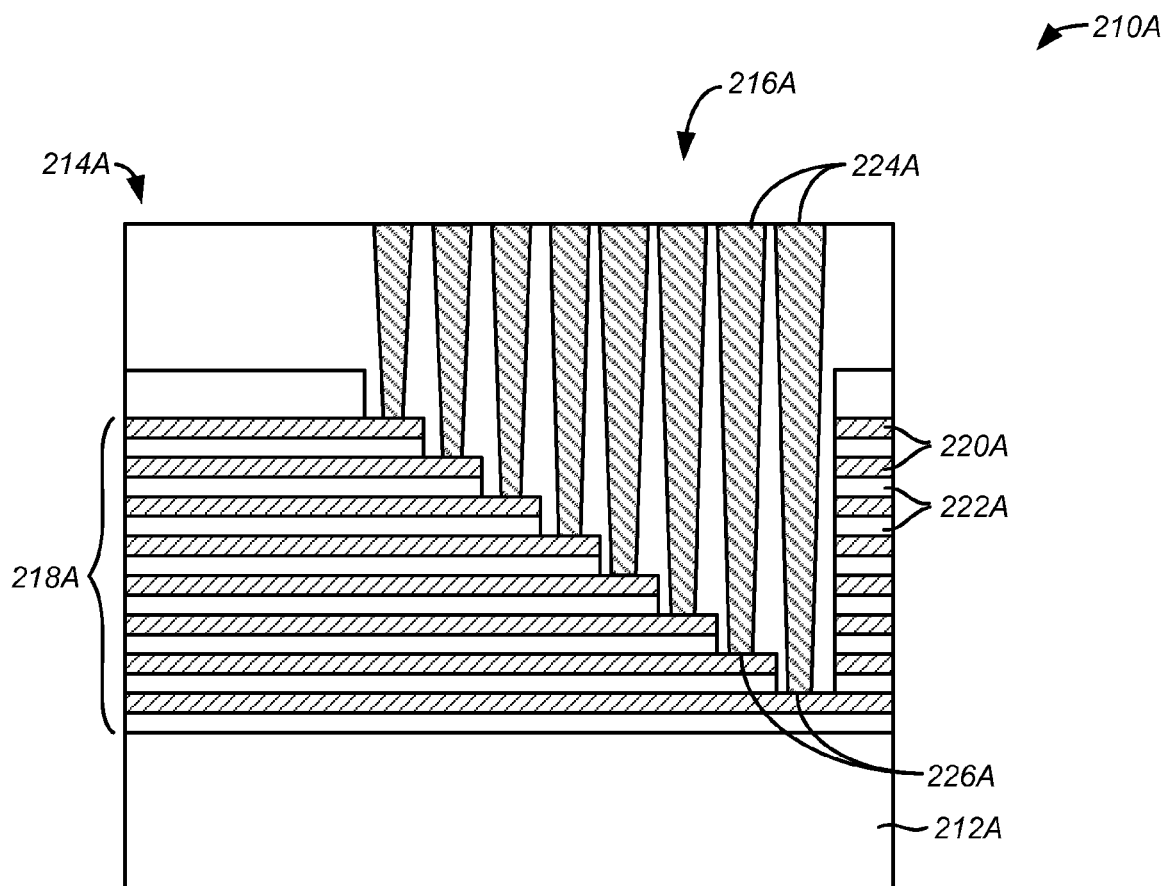


FIG. 2

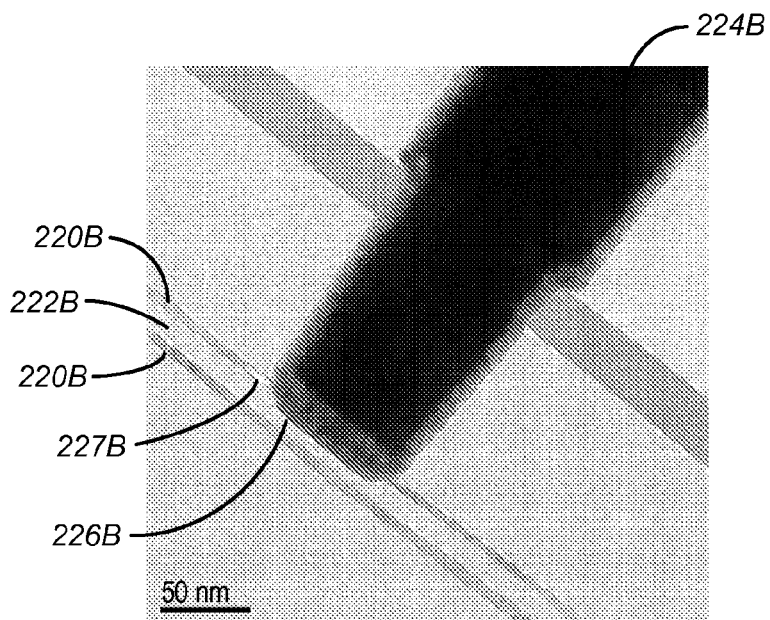


FIG. 2A

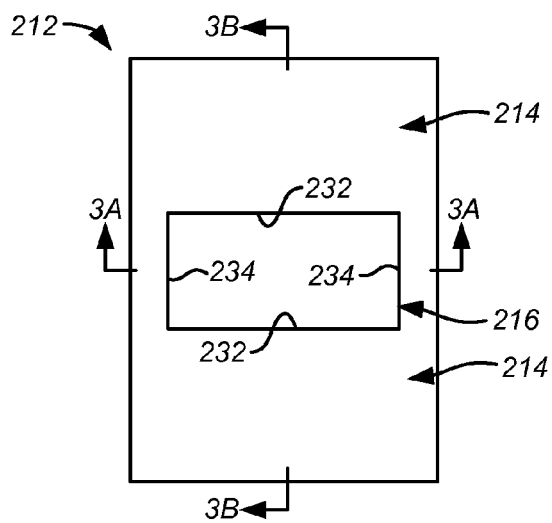


FIG. 3

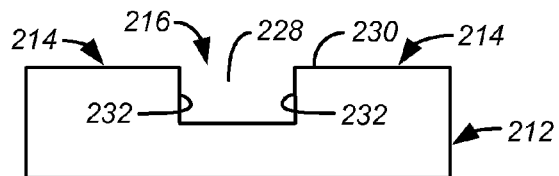


FIG. 3B

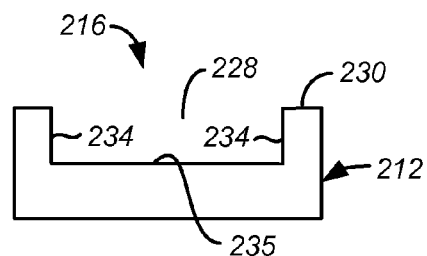


FIG. 3A

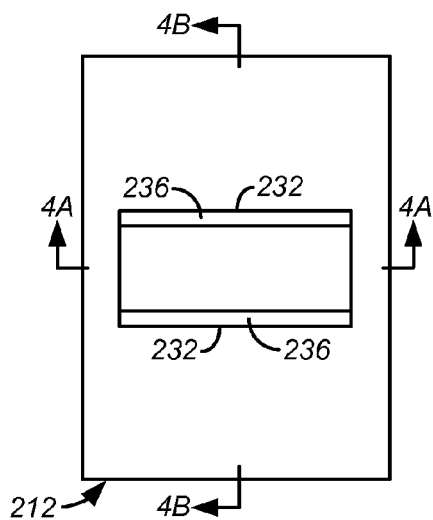


FIG. 4

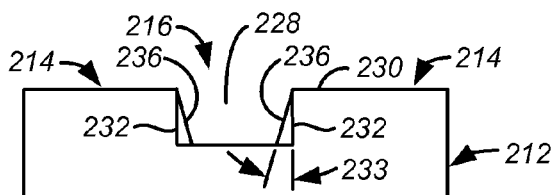


FIG. 4B

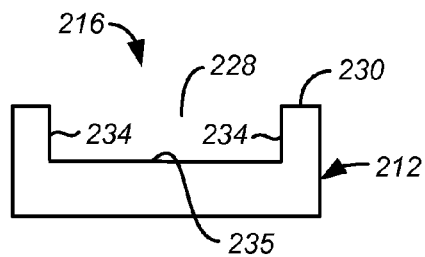


FIG. 4A

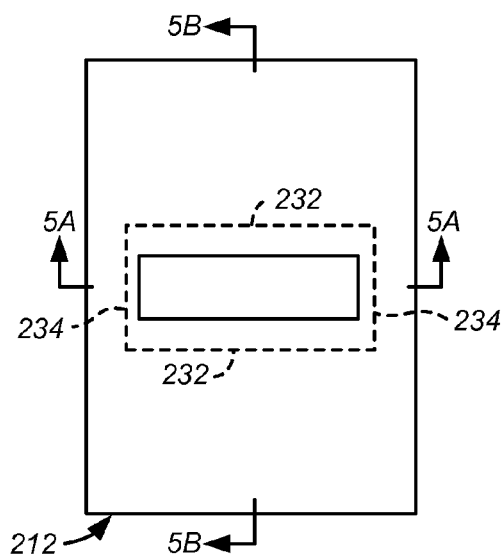


FIG. 5

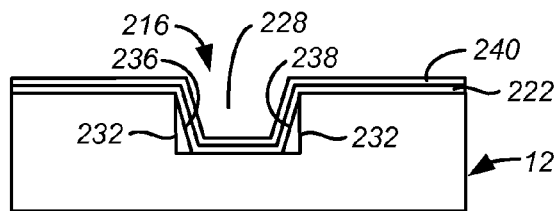


FIG. 5B

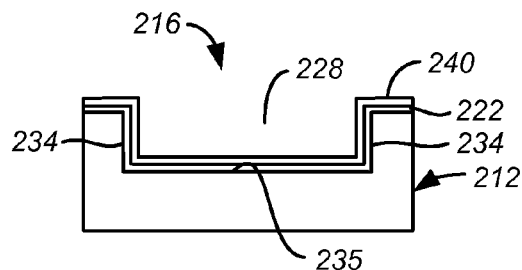


FIG. 5A

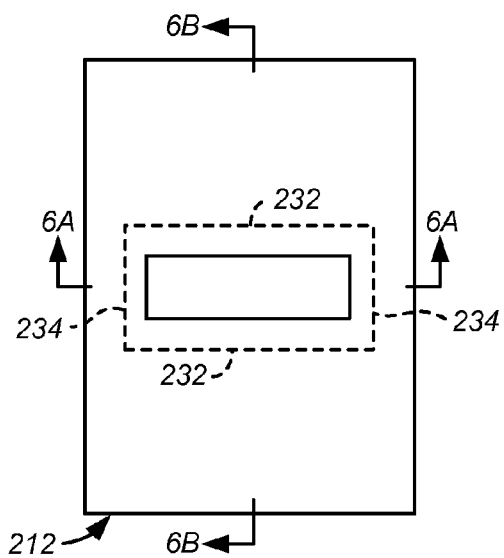


FIG. 6

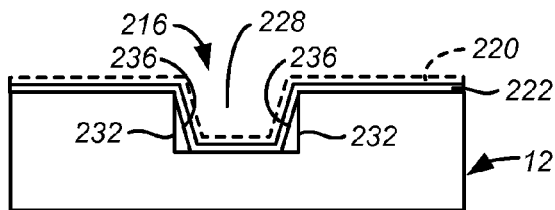


FIG. 6B

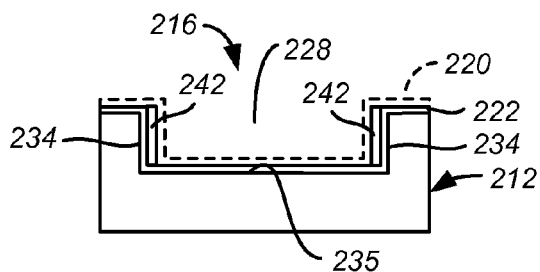


FIG. 6A

FIG. 7

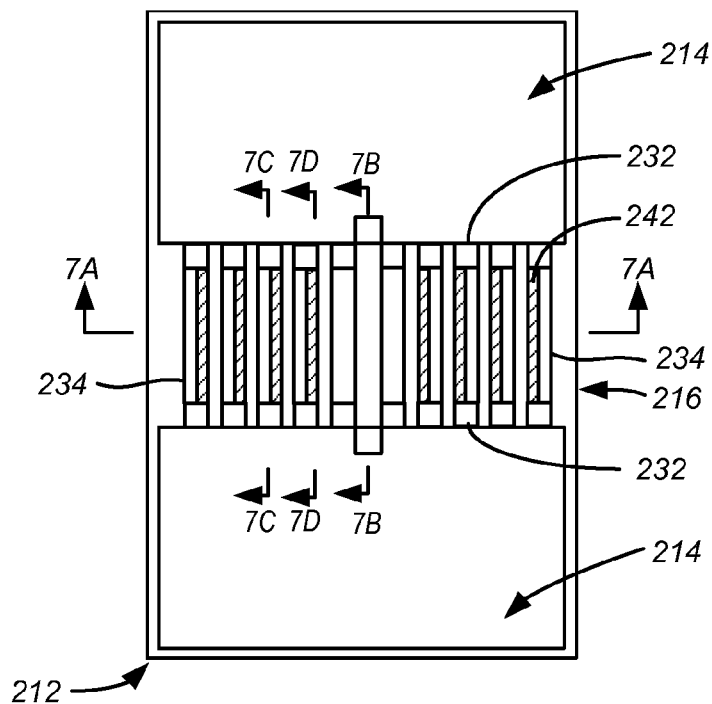


FIG. 7A

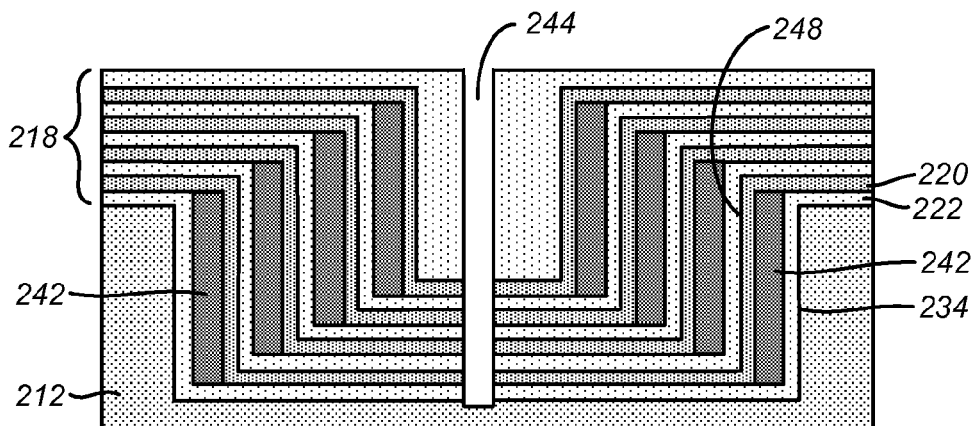


FIG. 7B

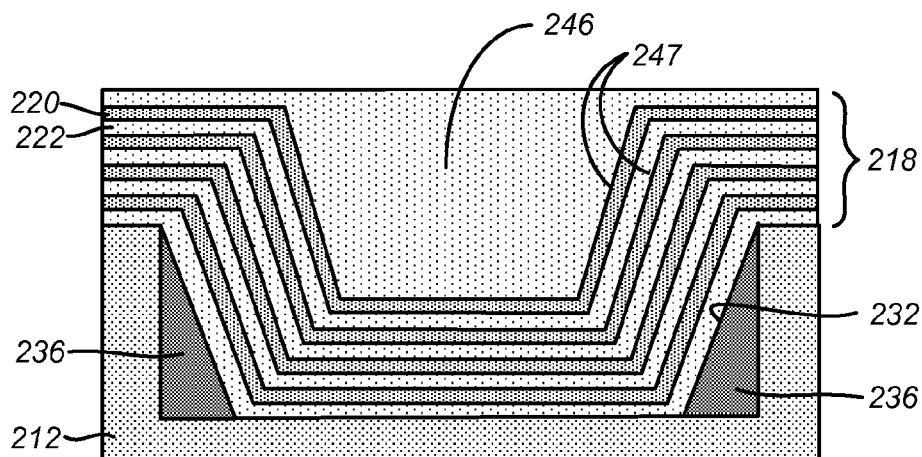


FIG. 7C

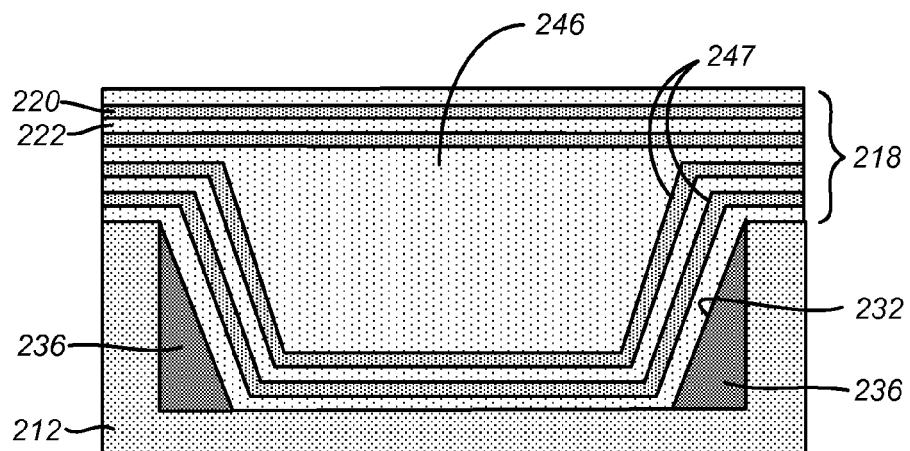


FIG. 7D

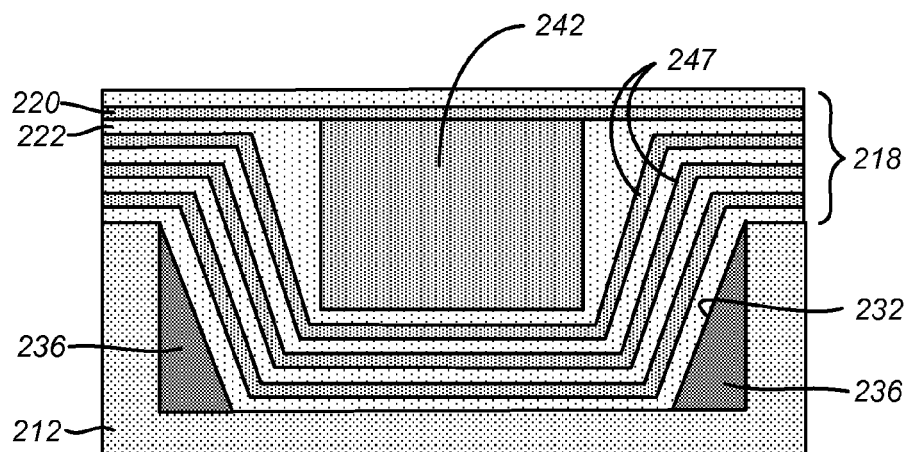


FIG. 8

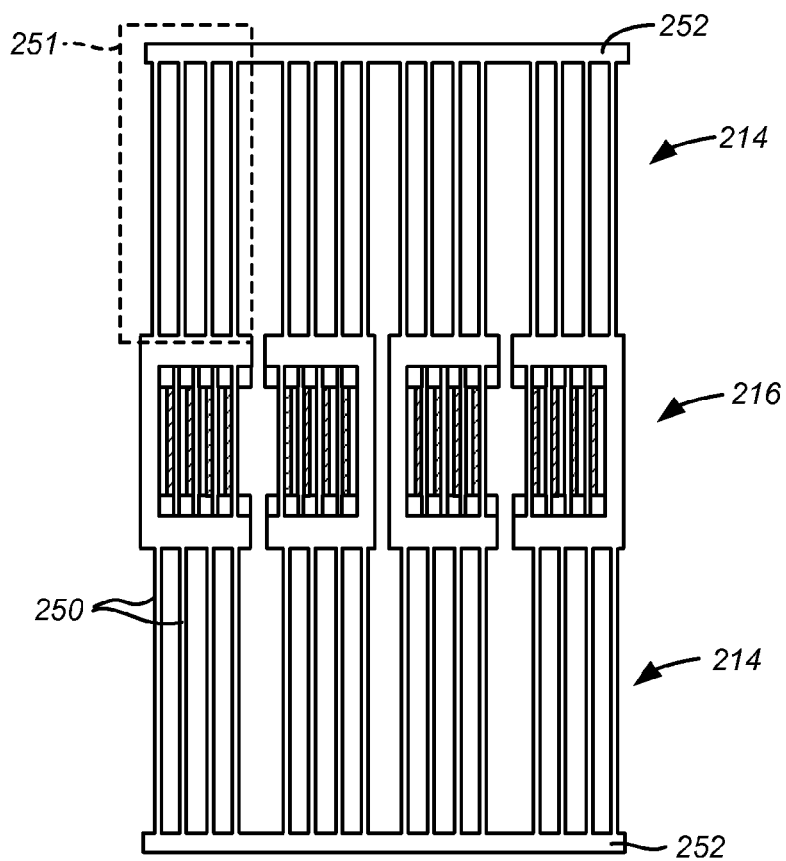
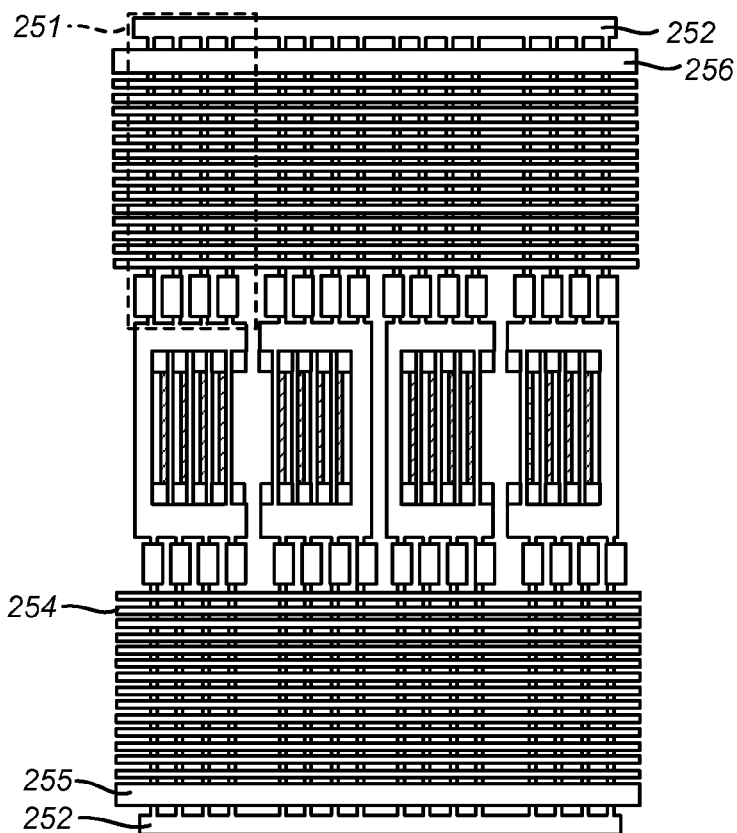


FIG. 9



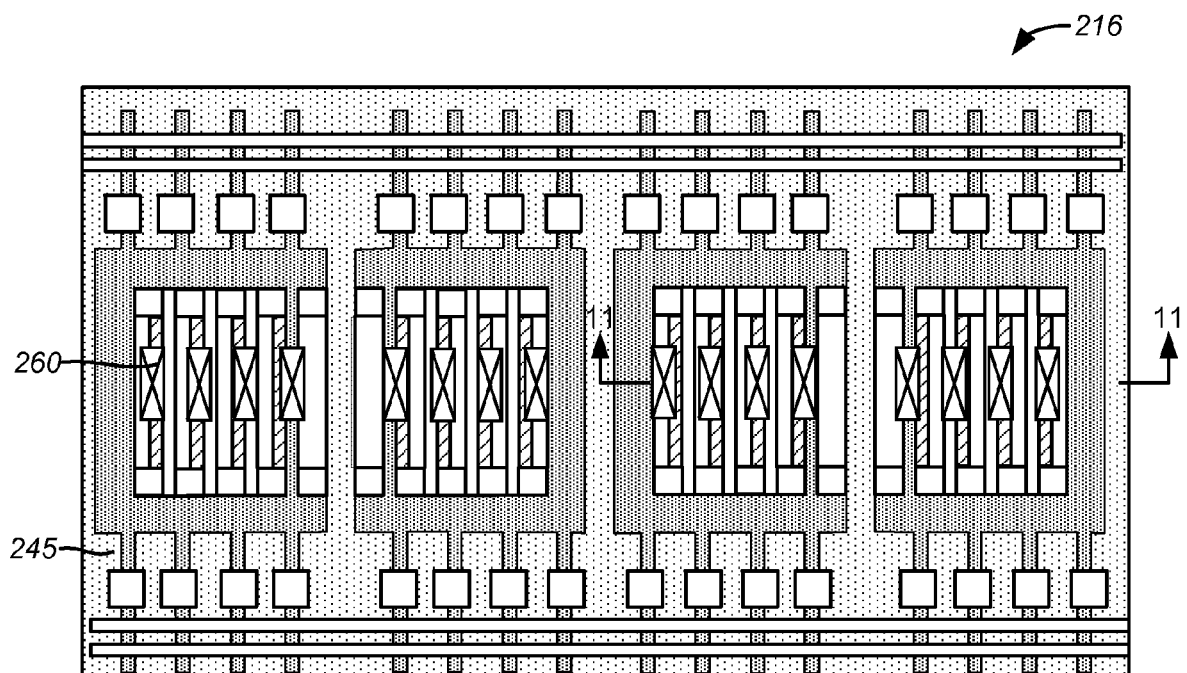


FIG. 10

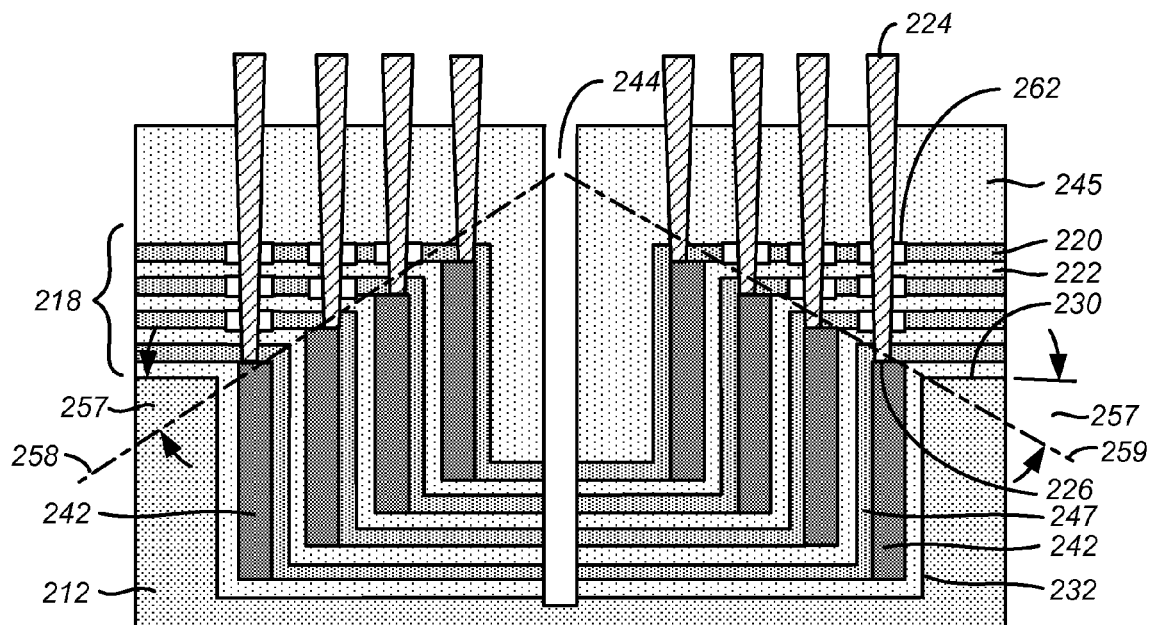


FIG. 11

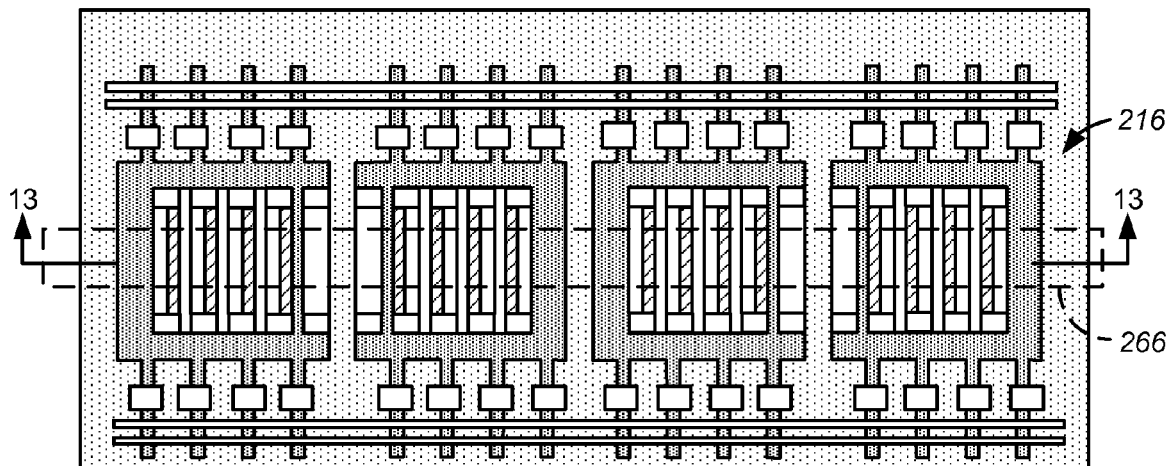


FIG. 12

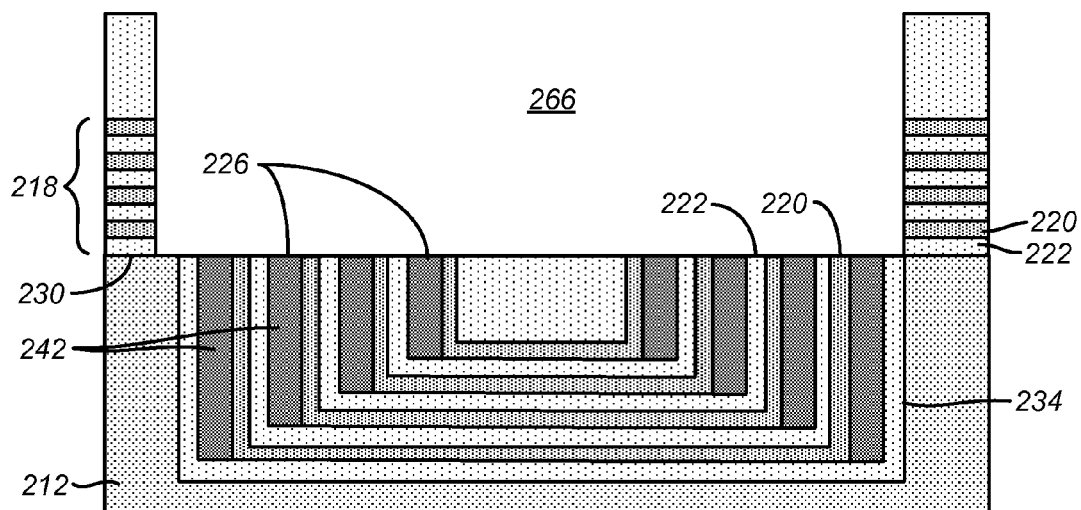


FIG. 13

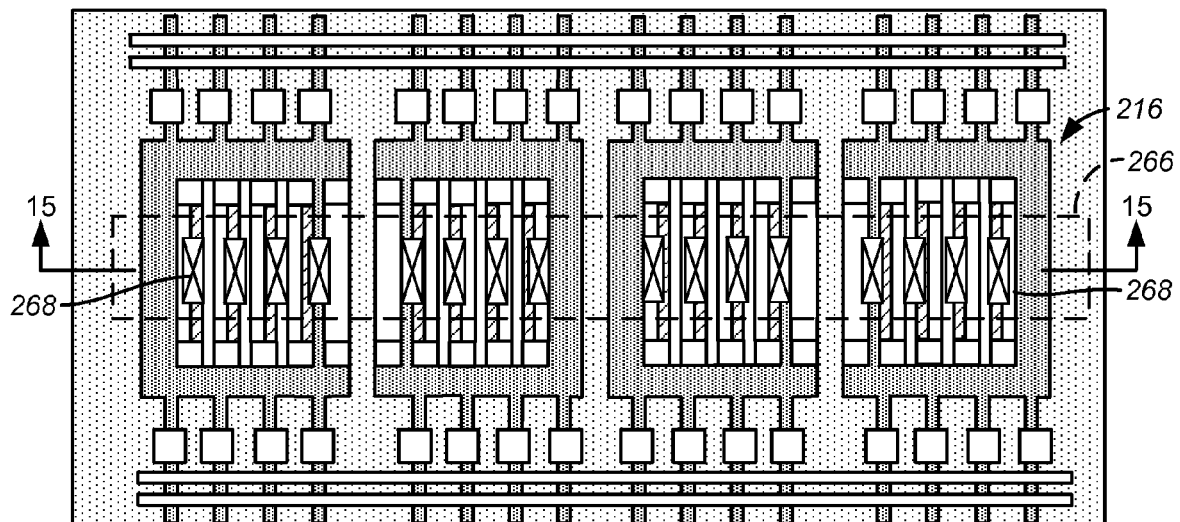


FIG. 14

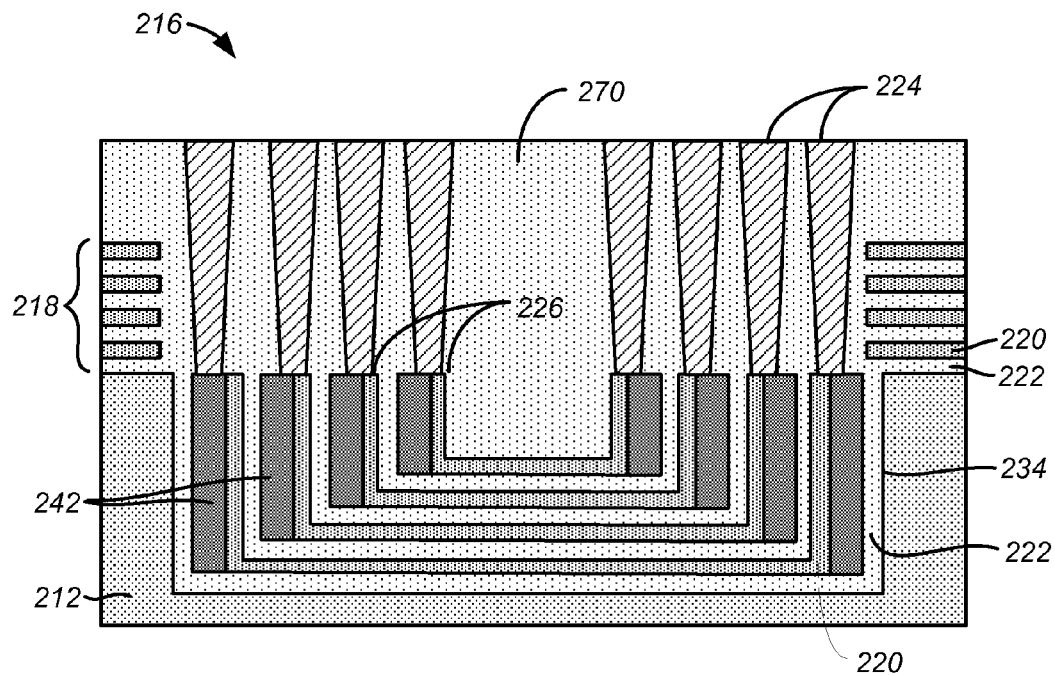
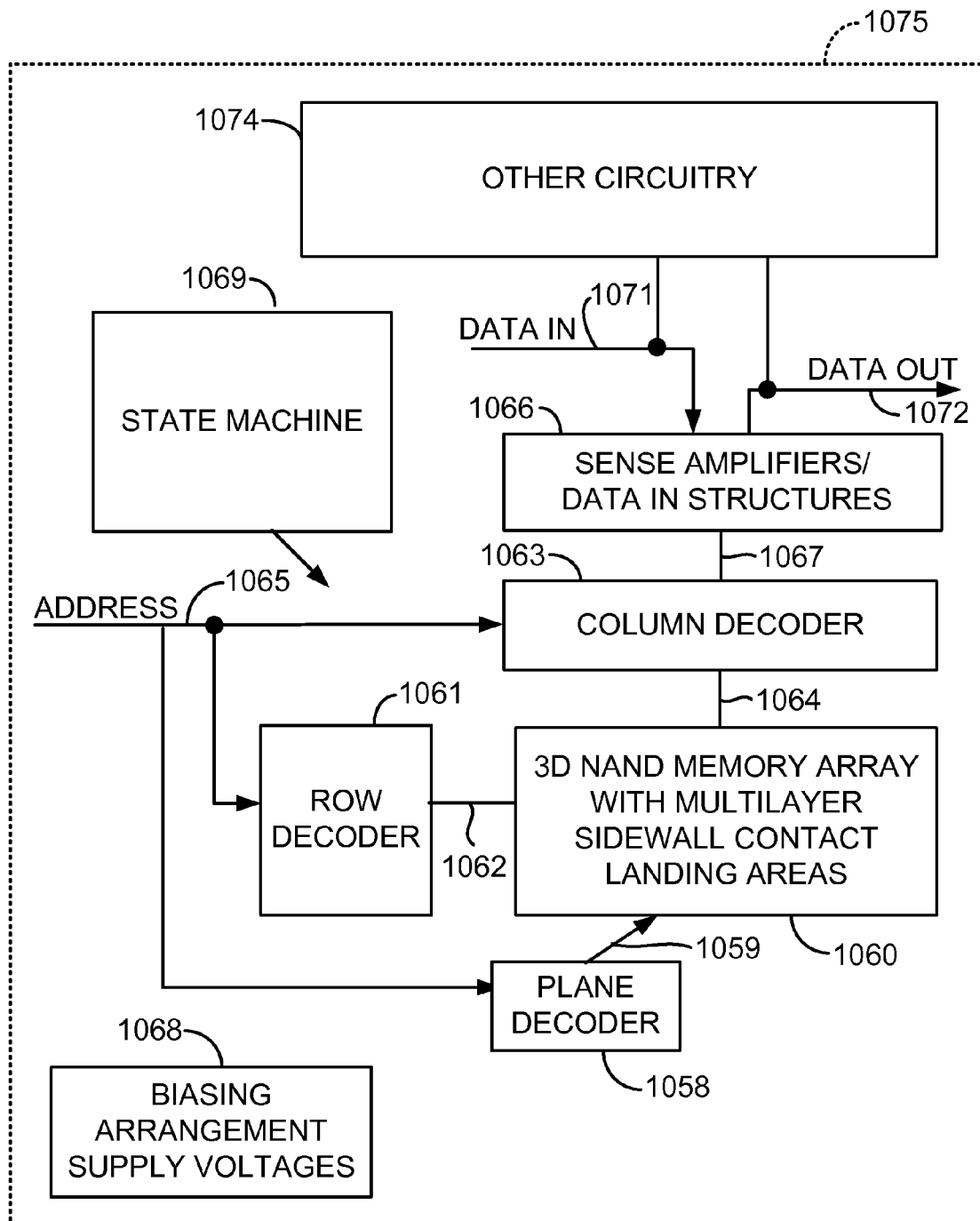


FIG. 15

**FIG. 16**

1

3-D IC DEVICE WITH ENHANCED CONTACT AREA

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation of U.S. patent application Ser. No. 13/948,508, filed 23 Jul. 2013, now U.S. Pat. No. 8,981,567 which application claims benefit of U.S. Provisional Patent Application No. 61/778,562, filed 13 Mar. 2013.

BACKGROUND

1. Field of the Invention

The present invention relates to three-dimensional integrated circuit (3-D IC) devices of the type including at least one array area and an associated contact area, and in particular to providing enhanced electrical contact at the contact area between interlayer conductors, such as bit line plugs, and increasingly thin semiconductor or conductor active layers in a stack of alternating active and insulating layers.

2. Description of Related Art

High density memory devices are being designed that comprise arrays of flash memory cells, or other types of memory cells. In some examples, the memory cells comprise thin film transistors which can be arranged in 3D architectures.

In one example, a 3D memory device includes a plurality of stacks of NAND strings of memory cells. The stacks include semiconductor strips, also referred to as active layers, separated by insulating layers. The 3D memory device includes an array including a plurality of word lines structures, a plurality of string select structures, and ground select lines, arranged orthogonally over the plurality of stacks. Memory cells including charge storage structures are formed at cross-points between side surfaces of the semiconductor strips in the plurality of stacks and the word line structures.

SUMMARY

A device includes a substrate having an upper surface and a recess extending into the substrate from the upper surface. The recess has a bottom and sides extending between the upper surface and the bottom. The sides include first and second sides oriented transversely to one another. A stack of alternating active and insulating layers overlie the upper surface of the substrate and the recess. At least some of the active layers have an upper portion extending along an upper plane over and generally parallel to the upper surface and a lower portion extending along a lower plane over and generally parallel to the bottom. Each of the active layers has first and second upward extensions positioned along the first and second sides to extend from the lower portions of their respective active layers. Conductive strips adjoin the second upward extensions of the said active layers.

Some examples of the device can include one or more the following. The conductive strips can comprise sidewall spacers on sides of the second upward extensions. The second side can be oriented generally perpendicular to the upper surface with the first side being a downwardly and inwardly sloped side oriented at an acute angle to the upper surface. The conductive strips can have lower and upper ends, the lower ends being in the recess and extending to different depths in the recess, the upper ends being configured to connect to overlying conductors by interlayer conductors. The upper ends of the conductive strips can be at the same level, the same level being parallel to the upper surface, or at different levels relative to the upper surface. The upper ends of the conductive

2

strips, or both the upper end of the conductive strips and adjacent ones of the second upward extensions, can provide landing areas for the interlayer conductors.

A method for forming electrical connections with the active layers of a stack of alternating active and insulating layers of a device can be carried out as follows. A recess can be formed through the upper surface of in a substrate, the recess having a bottom and sides extending between the upper surface and the bottom, the sides comprising first and second sides oriented transversely to one another. A stack of alternating active and insulating layers are formed over the upper surface of the substrate and the recess in the following manner. The upper portion of each of a plurality of the active layers is formed to be along an upper plane and over and generally parallel to the upper surface. A lower portion of each of the plurality of active layers is formed to be along a lower plane and over and generally parallel to the bottom. First and second upward extensions of each of the plurality of active layers are positioned along the first and second sides and to extend from the lower portions of their respective active layers. Conductive strips, adjoining the second upward extensions of the plurality of active layers, are formed during the stack forming step.

Some examples of the method can include one or more the following. The recess forming step can include forming the first side as a downwardly and inwardly sloped first side oriented at an acute angle to the upper surface. The conductive strips forming step can be carried out forming the conductive strips as sidewall spacers on sides of the second upward extensions but not on sides of the first upward extensions. The recess forming step can include forming a generally rectangular recess having first, second, third and fourth sides with the first and third sides being opposite one another and being downwardly and inwardly sloped sides oriented at acute angles to the upper surface; and the conductive strips can be formed as sidewall spacers at the second and fourth sides but not at the first or third sides. Interlayer conductors can be formed to contact upper surfaces of the conductive strips, the upper surfaces defining landing areas for the interlayer conductors. The landing areas can extend along a landing area plane generally parallel to the upper surface or at an acute angle to the upper surface. The landing areas can be created by the upper ends of the conductive strips and adjacent ones of the second upward extensions.

Other aspects and advantages of the present invention can be seen on review of the drawings, the detailed description and the claims, which follow.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a perspective illustration of a 3D NAND memory array structure. Insulating material is removed from the drawing to expose additional structure for illustrative purposes.

FIG. 2 is a simplified cross-sectional view of a portion of an example of an IC device showing interlayer conductors contacting landing areas at a contact area.

FIG. 2A is an image showing an example of how an interlayer conductor can pass completely through an active layer with which is to be in electrical contact.

FIGS. 3-13 illustrate one example of process steps in the connection of interlayer conductors to landing areas at the contact area.

FIG. 3 is a top plan view of a substrate including array areas on either side of a recessed contact area, with FIGS. 3A and 3B taken along lines 3A-3A and 3B-3B of FIG. 3.

FIGS. 4-4B show the structure of FIGS. 3-3B after the formation of tapered spacers along the first sides of a recess in the contact area.

FIGS. 5-5B show the structure of FIGS. 4-4B after the conformal deposition of an insulating layer followed by a relatively thick conductive material.

FIGS. 6-6B illustrate the structure of FIGS. 5-5B after an anisotropic etch of the conductive material removing the conductive material from all surfaces except the generally vertical second sides, with the subsequent deposition of an active layer indicated by dashed lines in FIGS. 6A and 6B.

FIGS. 7-7D show the structure of FIGS. 6-6B following the repeat of the deposition and etching steps of FIGS. 5-6B to create a stack of alternating active and insulating layers overlying the array area and the contact area.

FIG. 8 is a simplified top plan view of two side-by-side structures of FIG. 7 but showing bit lines and source lines in the array areas created by additional processing steps.

FIG. 9 shows the structure of FIG. 8 after creating word lines over the bit lines within the array areas.

FIG. 10 is an enlarged view of the contact area of FIG. 9 showing the plan view locations of interlayer conductors shown in FIG. 11.

FIG. 11 is a cross-sectional view of a portion of the structure of FIG. 10 showing interlayer conductors passing through insulating spacers and contacting landing areas created by conductive strips and adjacent first upper extensions of the conductive layers.

FIGS. 12-15 illustrate an alternative to the example shown in FIGS. 10-11 as to how interlayer conductors are connected to landing areas.

FIG. 12 is an enlarged view of the contact area of FIG. 9 but outlining a region to be etched in dashed lines.

FIG. 13 shows the structure of FIG. 12 after etching the region indicated in FIG. 12 so that all of the landing areas lie in a single plane.

FIG. 14 shows the structure of FIG. 13 but indicating where the interlayer conductors shown in FIG. 15 will be created.

FIG. 15 shows the structure of FIGS. 13 and 14 after depositing an insulating material within the etched out region and forming interlayer conductors through the insulating material down to the landing areas.

FIG. 16 is a schematic diagram of an integrated circuit including a 3D NAND memory array.

DETAILED DESCRIPTION

The following description will typically be with reference to specific structural embodiments and methods. It is to be understood that there is no intention to limit the invention to the specifically disclosed embodiments and methods but that the invention may be practiced using other features, elements, methods and embodiments. Preferred embodiments are described to illustrate the present invention, not to limit its scope, which is defined by the claims. Those of ordinary skill in the art will recognize a variety of equivalent variations on the description that follows. Like elements in various embodiments are commonly referred to with like reference numerals. Also, unless otherwise specified, the terms insulators and conductors refer to electrical insulators and electrical conductors.

FIG. 1 is a perspective illustration of a 3D NAND memory array structure. Insulating material is removed from the drawing to expose additional structure for illustrative purposes. For example, insulating layers are removed between the semiconductor strips (e.g. 112-115) in stacks, and are removed between the stacks of semiconductor strips.

The multilayer array is formed on an insulating layer, and includes a plurality of word lines 125-1 WL, . . . , 125-N WL conformal with the plurality of stacks. The plurality of stacks includes semiconductor strips 112, 113, 114, 115. Semiconductor strips in the same plane are electrically coupled together by staircase structures, also referred to as bit line structures.

The shown word line numbering, ascending from 1 to N going from the back to the front of the overall structure, applies to even memory pages. For odd memory pages, the word line numbering descends from N to 1 going from the back to the front of the overall structure.

Stairstep structures 112A, 113A, 114A, 115A terminate semiconductor strips, such as semiconductor strips 112, 113, 114, 115, in each active layer of the structure. As illustrated, these stairstep structures 112A, 113A, 114A, 115A are electrically connected to different bit lines for connection to decoding circuitry to select planes within the array. These stairstep structures 112A, 113A, 114A, 115A can be patterned at the same time that the plurality of stacks are defined.

Stairstep structures 102B, 103B, 104B, 105B terminate semiconductor strips, such as semiconductor strips 102, 103, 104, 105. As illustrated, these stairstep structures 102B, 103B, 104B, 105B are electrically connected to different bit lines for connection to decoding circuitry to select planes within the array. These stairstep structures 102B, 103B, 104B, 105B can be patterned at the same time that the plurality of stacks are defined.

Any given stack of semiconductor strips is coupled to either the stairstep structures 112A, 113A, 114A, 115A, or the stairstep structures 102B, 103B, 104B, 105B, but not both. A stack of semiconductor strips has one of the two opposite orientations of bit line end-to-source line end orientation, or source line end-to-bit line end orientation. For example, the stack of semiconductor strips 112, 113, 114, 115 has bit line end-to-source line end orientation; and the stack of semiconductor strips 102, 103, 104, 105 has source line end-to-bit line end orientation. In an alternative, all the strips in one active layer of the block can terminate in the same staircase structure.

The stack of semiconductor strips 112, 113, 114, 115 is terminated at one end by the stairstep structures 112A, 113A, 114A, 115A, passes through SSL gate structure 119, ground select line GSL 126, word lines 125-1 WL through 125-N WL, ground select line GSL 127, and terminated at the other end by source line 128. The stack of semiconductor strips 112, 113, 114, 115 does not reach the stairstep structures 102B, 103B, 104B, 105B.

The stack of semiconductor strips 102, 103, 104, 105 is terminated at one end by the stairstep structures 102B, 103B, 104B, 105B, passes through SSL gate structure 109, ground select line GSL 127, word lines 125-N WL through 125-1 WL, ground select line GSL 126, and terminated at the other end by a source line (obscured by other parts of figure). The stack of semiconductor strips 102, 103, 104, 105 does not reach the stairstep structures 112A, 113A, 114A, 115A.

A layer of memory material separates the word lines 125-1 WL through 125-N WL, from the semiconductor strips 112-115 and 102-105. Ground select lines GSL 126 and GSL 127 are conformal with the plurality of stacks, similar to the word lines.

Every stack of semiconductor strips is terminated at one end by stairstep structures, and at the other end by a source line. For example, the stack of semiconductor strips 112, 113, 114, 115 is terminated at one end by stairstep structures 112A, 113A, 114A, 115A, and terminated on the other end by source line 128. At the near end of the FIG., every other stack of

semiconductor strips is terminated by the staircase structures **102B**, **103B**, **104B**, **105B**; and every other stack of semiconductor strips is terminated by a separate source line. At the far end of the figure, every other stack of semiconductor strips is terminated by the staircase structures **112A**, **113A**, **114A**, **115A**; and every other stack of semiconductor strips is terminated by a separate source line.

Bit lines and string select lines are formed in patterned conductor layers, such as the metal layers **ML1**, **ML2**, and **ML3**.

Transistors are formed at cross points between the semiconductor strips (e.g. **112-115**) and the word line **125-1 WL** through **125-N WL**. In the transistors, the semiconductor strip (e.g. **113**) acts as the channel region of the device. The semiconductor strips (e.g. **112-115**) can act as the gate dielectric for the transistors.

String select structures (e.g. **119**, **109**) are patterned during the same step that the word lines **125-1 WL** through **125-N WL** are defined. Transistors are formed at cross points between the semiconductor strips (e.g. **112-115**) and the string select structures (e.g. **119**, **109**). These transistors act as string select switches coupled to decoding circuitry for selecting particular stacks in the array.

In an alternative, the active layer is patterned with word lines and the channels can be vertical between the stacks. See, for example, commonly owned U.S. Patent Application Publication No. 2012/0182808, filed 19 Jan. 2011, entitled Memory Device, Manufacturing Method And Operating Method Of The Same, by inventors Hang-Ting Lue and Shi-Hung Chen, which is incorporated by reference as if fully set forth herein.

The 3D memory device shown in FIG. 1 uses finger VG (vertical gates), like commonly owned U.S. Patent Publication No. 2012/0182806, filed Apr. 1, 2011, entitled Memory Architecture of 3D Array With Alternating Memory String Orientation and String Select Structures by inventors Shih-Hung Chen and Hang-Ting Lue. The vertical gate (VG) structure and other 3D structures can be made using very thin film active layers, such as 1 to 10 nanometers thick, may be a solution to help solve some of the problems. However, using such a thin film active layer can create challenges in the connection of the interlayer conductors to the landing areas. Problems associated with making contact to very thin film active layers will be discussed with reference to FIGS. 2 and 2A.

FIG. 2 is a simplified cross-sectional view of a portion of an IC device **210A** including a substrate **212A**, the substrate including an array area **214A** and a contact area **216A**. A stack **218A** of alternating active layers **220A** and insulating layers **222A** overlie the array area and the contact area. Interlayer conductors **224A** extend to the landing areas **226A** of the active layers **220A**. FIG. 2A is an image showing how, due to the thinness of active layers **220B**, an interlayer conductor **224B** can be formed so that it passes completely through an active layer **220B**; doing so can make the step critical in manufacturing and might limit the contact area to the periphery of interlayer conductor **224B**. For perspective on the relative sizes of the interlayer conductors **224B** and active layers **220B**, the line at the lower left-hand corner of FIG. 2A is 50 nm long. In addition to passing through active layer **220B**, use of thin film active layers **220B** must deal with a problem caused by the consumption of silicon during the silicide formation following formation of interlayer conductors **224B**. This problem is illustrated at position **227B**, which shows up as a lighter area, indicating consumption of silicon within active layer **220B**. This creates another way that the contact area between active layer **220B** and interlayer con-

ductor **224B** might be reduced. In one example, when the tungsten in the interlayer conductor **224B** contacts the silicon in active layer **220B**, a reaction can cause formation of tungsten silicide (WSi_x). Silicon to fuel the reaction can be drawn into the via and out of the thin film of active layer **220B** creating a void.

FIGS. 3-13 illustrate one example of process steps used for the connection of interlayer conductors **224** to the landing areas **226** at the contact area **216**.

FIG. 3 is a top plan view of a substrate **212** including first and second array areas **214** on either side of a recessed contact area **216**. Contact area **216** is formed by a recess **228** extending into substrate **212** from an upper surface **230** of the substrate. FIGS. 3A and 3B are taken along line 3A-3A of FIG. 3 to show first sides **232**, and along line 3B-3B of FIG. 3 to show second sides **234**, and to illustrate recess **228**. Recess **228** is defined on two sides by first sides **232**, by second sides **234** connecting the first sides, and by bottom **235**.

FIGS. 4-4B show the structures of FIGS. 3-3B after the formation of a tapered spacer **236** along the first sides **232** so that recess **228** is defined by generally vertical second sides **234** and sloped first sides **232** created by tapered spacers **236**. The surface of tapered spacer **236** slopes downwardly an angle **233** to the vertical. The choice of the material for tapered spacers **236** is determined in part by the desired process for forming tapered spacers **236**. In one example, tapered spacers are polysilicon but other materials, such as other semiconductors or metals, can also be used. The sloped profile can be made using various techniques. One technique uses lithography to make the sloped profile. Starting with the trench like recess **228** of FIGS. 3A and 3B with its vertical sides, a photoresist is applied to most of array area **214** to protect the second sides **234** while exposing first sides **232**. This is followed by an anisotropic etch, or etch with some ion bombardment, to form the sloped profile on the first sides **232**. In this technique, it may not be necessary to create tapered spacers **236**. Another technique uses an etching process. An etch stop layer, such as a nitride layer, is deposited on the bottom **235** of the trench like recess **228**. After the etch stop layer deposition, a material, such as polysilicon, is deposited within recess **228**. Most of the material within recess **228** is removed leaving a tapered spacer layer, similar to tapered spacer **236**, along all four sides **232**, **234** defining recess **228**. Using a photoresist mask and suitable etching steps, the tapered spacer layers along second sides **234** are removed leaving tapered spacers **236** only along first sides **232**.

FIGS. 5-5B shows the structure of FIGS. 4-4B after the conformal deposition of an insulating layer **222** followed by the conformal deposition of a relatively thick layer of conductive material **240**. In one example, insulating layer **222** is an oxide, such as silicon dioxide; other materials, such as SiN , SiON and Al_2O_3 , can also be used. The insulating material may also be a multi-layer, such as silicon oxide/silicon nitride/silicon oxide (ONO), silicon oxide/high-k dielectric/silicon oxide (O/high-k/O). In this example, conductive material **240** is doped polysilicon (using dopants such as As, P), but, for example, materials such as a metal or combination of metals, including Al, Cu, W, Ti, Co, Ni, can also be used. The conductive material **240** can also be metal compounds, such as TiN/TaN/AlCu , or semiconductor compounds, such as heavily doped silicides including TiSi , CoSi . The dashed line in FIG. 5 indicates the location of the sides **232**, **234** of FIG. 3.

FIGS. 6-6B illustrate the structure of FIGS. 5-5B after an anisotropic etch of the conductive material **240**. Doing so removes the portion of conductive material **240** from the horizontal surfaces above bottom **235** within recess **228** and

7

over the upper surfaces **230** of array areas **214**. Sloped first sides **232** are sloped with angle **233** being sufficiently large to ensure that conductive material **240** is also removed from the sloped first sides **232** during the anisotropic etch. Angle **233** depends largely on the particular material used for tapered spacers **236** and the anisotropic etch used. However, the anisotropic, that is directional, characteristic of the anisotropic etch, results in formation of sidewall spacers on the upward extensions of the active layers, providing generally vertically extending conductive strips **242** of conductive material **240** along second sides **234**. Conductive material **240** is completely removed from the sloped first sides **232** as shown in FIG. 6A, while in FIG. 6B conductive strips **242** are shown at second sides **234**. This is followed by the conformal deposition of an active layer **220**, shown in dashed lines, which conforms to the contour of insulating layer **222** and conductive strips **242**. Active layer **220** is a semiconductive or conductive material, such as polysilicon, but other materials such as discussed above with regard to conductive material **240** can also be used. An alternative order can be used for the deposition of the active and insulating layers **220**, **222**. In addition, conductive strips **242** could be created by other than depositing conductive material **240** on all of the surfaces defining recess **228**. For example, conductive strips **242** could be created by patterned etching rather than sidewall spacer processes, or by other technologies.

FIGS. 7-7D show the structure of FIG. 6 following the repeat of the deposition and etching steps of FIGS. 5-6B to create a stack **218** of alternating active and insulating layers **220** and **222** overlying the array areas **214** and the contact area **216**. FIGS. 7A-7D are enlarged cross-sectional views relative to FIG. 7. Stack **218** of layers **220**, **222** extends conformally over upper surface **230** of array areas **214** and also conformally over recessed contact area **216**, that is over the bottom **235**, sloped first sides **232** and second sides **234**. FIGS. 7-7A indicate that stack **218** of alternating active and insulating layers **220**, **222** within the recess **228** have been cut so that a gap **244** separates the stacks into left and right sides. Separating the active and insulating layers **220**, **222** within recess **228** allows using two second sides **234** for different blocks of cells as illustrated by block **251** in FIG. 8. Stack **218** includes first and second upward extensions **247**, **248** of active layers **220** within recess **228** along first sides **232** and second sides **234**, respectively. Creation of stack **218** is then followed by covering the structure with an insulating material, such as silicon oxide.

FIG. 8 is a simplified top plan view of two side-by-side structures of FIG. 7 following etching of stack **218** of active and insulating layers **220**, **222** to create layers of local bit lines **250** and source lines **252** in array areas **214**. In some examples, the entire stack **218** is etched at the same time. The same etch pattern may or may not be used for each block **251** of local bit lines **250**. The processing steps typically do not affect contact area **216**. In some examples, source lines **252** can correspond to source line **128** in FIG. 1. Bit lines **250** are local bit lines within the active layers. As is discussed in more detail below, interlayer conductors **224** are used to connect the layers of local bit lines **250** to global bit lines (not shown), such as the global bit lines shown as the topmost elements extending generally from the upper left towards the lower right in FIG. 1.

FIG. 9 shows an aerial view of the structure of FIG. 8 after creating word lines **254** within array areas **214**. Word lines **254** correspond to word lines **125-1** through **125-N** in FIG. 1. Also created are a gate select line **255** at one end and a string select line **256** at the opposite end. Ground select line **255** corresponds to ground select lines **126**, **127** of FIG. 1 and is

8

used to connect source line **252** to local bit lines **250**. String select line **256** corresponds to string select lines **1064** in FIG. 16. In this example, active layers **220** are used to form local bit lines. In other examples, active layers **220** can be used to create source lines instead of bit lines.

After formation of the structure of FIG. 9, an interlayer dielectric fill **245**, see FIG. 10, is formed over array areas **214** and contact area **216**. Interlayer dielectric **245** can be an insulator such as silicon oxide or as discussed above with reference to insulating layer **222**. As discussed below, contact vias can be formed in the interlayer dielectric **245** to expose the landing areas **226** created by first upward extensions **247** and their adjacent conductive strips **242**. The vias can be filled with interlayer conductors. As discussed above, array area structures including global bit lines, string select lines and the like can be formed over the interlayer dielectric and make contact to the interlayer conductors.

FIG. 10 is an enlarged aerial or layout view of a portion of the structure of FIG. 9 including contact area **216**. FIG. 10 shows the plan view locations **260** for the interlayer conductors **224** shown in FIG. 11. FIG. 11 is a cross-sectional view of a portion of the structure of FIG. 10 showing landing areas **226** created by conductive strips **242** and adjacent upward extensions **247** of active layer **220**. The vertical conductive strips **242** have lower sides in the recess contacting respective active layers of the stack at different depths in the recess, and have upper sides that lie nominally along the planes **258**, **259**, where "nominally" means that they are lie in the plane within limitations of manufacturing processes and within manufacturing variations. The conductive strips are configured to connect, or provide contact landing areas for connection of, corresponding active layers at different depths in the recess to overlying conductors through interlayer conductors **224**. Insulating spacers **262** are formed in active layers **220** at positions overlying landing areas **226**. One way to do so is to form a via for each interlayer conductor **224** so that it passes through interlayer dielectric **245** and through the active layers **220** overlying the landing area **226** for that interlayer conductor. This can be followed by oxidizing the surfaces of active layers **220** opening onto the vias to create the insulating spacers **262** from the oxidized material of the active layers. As shown in FIG. 11, the interlayer conductors in contact with the conductive strips, the interlayer conductors have a nominal width, where "nominal" means that have the named width within limitations of manufacturing processes and within manufacturing variations. Though not illustrated in this drawing, the active layers can be much thinner than that nominal width. The conductive strips however, can have a pitch (distance from the center of one conductive strip to the center of its adjacent conductive strip) at their upper sides that is at least as large as, or larger than, the nominal width of the interlayer conductors. This provides significant alignment margin, simplifying the manufacturing of the structures, even for active layers that can be on the order of ten or twenty nanometers (or less) thick, which can be considered a critical thickness at which making contact using a vertical via to an individual active layer can be very difficult to achieve with reasonable reliability.

Alternatively, the vias can be lined with an insulating layer to create the insulating spacers **262**. Conductive material is then deposited within the vias to pass through interlayer dielectric **245**, through the openings in insulating spacers **262**, and down to landing areas **226** to create interlayer conductors **224**. Therefore, interlayer conductors **224** extend through the interlayer dielectric **245**, through overlying active layers **220** and down to landing areas **226**. In this way, interlayer conductors **224** contact associated landing areas **226** but

are electrically isolated from overlying active layers **220**. Interlayer conductors **224** connect the landing areas **226** for the local bit lines **250** to the global bit lines (not shown) in an embodiment in which the active layers **220** are used to form local bit lines. In this example, landing areas **226** within contact area **216** extend along two different planes **258**, **259**, each at an acute angle **257** to upper surface **230**. Therefore, in this example the upper ends of conductive strips **242** are at different levels relative to upper surface **230**.

FIGS. **12-15** illustrate an alternative to the example shown in FIGS. **10-11** as to how interlayer conductors **224** are connected to landing areas **226**.

FIG. **12** is an enlarged view of the central portion of the structure of FIG. **9** illustrating contact area **216** but outlining a region **266** to be etched in dashed lines. FIG. **13** is a cross-sectional view taken along line **13-13** of FIG. **12** after etching region **266**. After etching region **266**, all of the landing areas **226** extend along a single plane oriented generally parallel to upper surface **230**. So, in this example, the vertical conductive strips **242** have lower sides in the recess contacting respective active layers of the stack at different depths in the recess, and have upper sides that lie nominally in a single plane. The conductive strips are configured to connect, or provide contact landing areas for connection of, corresponding active layers at different depths in the recess to overlying conductors through interlayer conductors **224**.

FIG. **14** shows the structure of FIG. **13** but indicates at locations **268** where the interlayer conductors **224** will be created. FIG. **15** shows the structure of FIGS. **13** and **14** after depositing an insulating material **270** within the etched out region **266** of FIG. **13**. The upper ends of conductive strips **242** provide contact landing areas **226** for connection of overlying interlayer conductors **224** to corresponding active layers **220**. The contact landing areas **226** are at the same level relative to upper surface **230** of substrate **212**, and thus are parallel to the upper surface **230**. An example of insulating material **270** is silicon dioxide but other insulating materials as discussed above with regard to insulating layer **222** can also be used. Openings are then formed through insulating material **270** followed by forming interlayer conductors **224** through insulating material **270** down to landing areas **226**. Although the procedure described in FIGS. **12-15** requires an additional mask to create region **266**, as compared to the procedure described with regard to FIGS. **10** and **11**, the isolation between the contact at landing areas **226** and the unselected insulating layers **222** can be greater with the procedure of FIGS. **12-15**.

FIG. **16** is a schematic diagram of an integrated circuit including a 3D NAND memory array. The integrated circuit **1075** includes a 3D NAND flash memory array on a semiconductor substrate **212**. Substrate **212** includes an array area **214** and a recessed contact area **216** with a stack **218** of alternating active layers **220** and insulating layers **222** at both the array area **214** and recessed contact area **216**. A row decoder **1061** is coupled to a plurality of word lines **1062**, and arranged along rows in the memory array **1060**. A column decoder **1063** is coupled to a plurality of SSL lines **1064**, including string select structures, arranged along columns corresponding to stacks in the memory array **1060** for reading and programming data from the memory cells in the array **1060**. A plane decoder **1058** is coupled to a plurality of planes in the memory array **1060** via bit lines **1059**. Addresses are supplied on bus **1065** to column decoder **1063**, row decoder **1061** and plane decoder **1058**. Sense amplifiers and data-in structures in block **1066** are coupled to the column decoder **1063** in this example via data bus **1067**. Data is supplied via the data-in line **1071** from input/output ports on the integrated

circuit **1075** or from other data sources internal or external to the integrated circuit **1075**, to the data-in structures in block **1066**. In the illustrated embodiment, other circuitry **1074** is included on the integrated circuit, such as a general purpose processor or special purpose application circuitry, or a combination of modules providing system-on-a-chip functionality supported by the NAND flash memory cell array. Data is supplied via the data-out line **1072** from the sense amplifiers in block **1066** to input/output ports on the integrated circuit **1075**, or to other data destinations internal or external to the integrated circuit **1075**.

A controller implemented in this example using bias arrangement state machine **1069** controls the application of bias arrangement supply voltage generated or provided through the voltage supply or supplies in block **1068**, such as read, erase, program, erase verify and program verify voltages.

The controller can be implemented using special-purpose logic circuitry as known in the art. In alternative embodiments, the controller comprises a general-purpose processor, which may be implemented on the same integrated circuit, which executes a computer program to control the operations of the device. In yet other embodiments, a combination of special-purpose logic circuitry and a general-purpose processor may be utilized for implementation of the controller.

The above descriptions may have used terms such as above, below, top, bottom, over, under, et cetera. These terms may be used in the description and claims to aid understanding of the invention and not used in a limiting sense. Any and all patent applications and printed publications referred to above are incorporated by reference.

While the present invention is disclosed by reference to the preferred embodiments and examples detailed above, it is to be understood that these examples are intended in an illustrative rather than in a limiting sense. It is contemplated that modifications and combinations will occur to those skilled in the art, which modifications and combinations will be within the spirit of the invention and the scope of the following claims.

What is claimed is:

1. A device comprising:

a substrate comprising an upper surface and a recess extending into the substrate from the upper surface; the recess having a bottom and sides extending between the upper surface and the bottom, the sides comprising first and second sides oriented transversely to one another; a stack of alternating active and insulating layers overlying the recess;

each of a plurality of said active layers having a lower portion extending along a lower plane over and generally parallel to the bottom;

each of the plurality of said active layers comprising first and second upward extensions positioned along the first and second sides and extending from the lower portions of their respective active layers;

the second upward extensions having lengths with lower ends towards the bottom and upper ends; and

a plurality of conductive strips adjoining the second upward extensions of the plurality of said active layers along their lengths towards but not past their upper ends.

2. The device of claim 1, wherein:

the stack of alternating active and insulating layers also overlies the upper surface of the substrate and the recess; and

each of the plurality of active layers also has an upper portion extending along in a plane over and generally parallel to the upper surface.

11

3. The device of claim 2, wherein the first upward extensions connect the upper and lower portions of their respective active layers.

4. The device of claim 2, wherein:

the upper surface comprises an array area adjacent to the recess; and

the stack of alternating active and insulating layers comprises elements of a memory array at the array area.

5. The device of claim 1, wherein the second upward extensions are oriented generally perpendicular to the upper surface and the first upward extensions are downwardly and inwardly sloped at an acute angle to the upper surface.

6. The device of claim 1, wherein:

the recess is a generally rectangular recess with a third side opposite the first side and a fourth side opposite the second side; and

the second and fourth sides are oriented generally perpendicular to the upper surface and the first and third side are downwardly and inwardly sloped oriented at acute angles to the upper surface.

7. The device of claim 1, wherein the upper surface and the bottom are generally parallel to one another.

8. A device comprising:

a substrate comprising an upper surface and a recess extending into the substrate from the upper surface;

the recess having a bottom and sides extending between the upper surface and the bottom, the sides comprising first and second sides oriented transversely to one another; a stack of alternating active and insulating layers overlying the recess;

each of a plurality of said active layers having a lower portion extending along a lower plane over and generally parallel to the bottom;

each of the plurality of said active layers comprising first and second upward extensions positioned along the first and second sides and extending from the lower portions of their respective active layers; and

a plurality of conductive strips adjoining the second upward extensions of the plurality of said active layers, the plurality of conductive strips comprising sidewall spacers on sides of the second upward extensions.

9. A device comprising:

a substrate comprising an upper surface and a recess extending into the substrate from the upper surface;

the recess having a bottom and sides extending between the upper surface and the bottom, the sides comprising first and second sides oriented transversely to one another; a stack of alternating active and insulating layers overlying the recess;

each of a plurality of said active layers having a lower portion extending along a lower plane over and generally parallel to the bottom;

each of the plurality of said active layers comprising first and second upward extensions positioned along the first and second sides and extending from the lower portions of their respective active layers; and

a plurality of conductive strips adjoining the second upward extensions of the plurality of said active layers, the conductive strips having lower and upper ends, the lower ends being in the recess, the upper ends being configured to connect to overlying conductors by interlayer conductors.

10. The device of claim 9, wherein the upper ends of at least some of the conductive strips are at the same level, the same level being parallel to the upper surface.

11. The device of claim 9, wherein the upper ends are at different levels relative to the upper surface.

12

12. The device of claim 9, wherein the upper ends of the conductive strips provide landing areas for the interlayer conductors.

13. The device of claim 9, wherein the upper ends of the conductive strips and adjacent ones of the second upward extensions provide landing areas for the interlayer conductors.

14. A method for forming electrical connections with active layers of a stack of alternating active and insulating layers of a device, the method comprising:

forming a recess in a substrate, the substrate comprising an upper surface with the recess extending into the substrate from the upper surface, the recess having a bottom and sides extending between the upper surface and the bottom, the sides comprising first and second sides oriented transversely to one another;

forming a stack of alternating active and insulating layers over the recess;

the stack forming step comprising:

forming a lower portion of each of the plurality of active layers to be along a lower plane and over and generally parallel to the bottom; and

forming first and second upward extensions of each of the plurality of active layers to be positioned along the first and second sides and to extend from the lower portions of their respective active layers; and

during the stack forming step, forming conductive strips adjoining the second upward extensions of the plurality of active layers.

15. The method of claim 14, wherein the stack forming step also forms: (a) the said stack of alternating active and insulating layers over the upper surface of the substrate; and (b) an upper portion of each of a plurality of the active layers to be along a plane and over and generally parallel to the upper surface.

16. The method of claim 14, wherein the recess forming step comprises forming the first side as a downwardly and inwardly sloped first side oriented at an acute angle to the upper surface.

17. The method of claim 16, wherein:

the recess forming step comprises forming the second side oriented generally perpendicular to the upper surface;

the conductive strips forming step comprising depositing a layer of conductive material along the bottom and sides of the recess, and anisotropically etching the conductive material; and

selecting the acute angle of the sloped first side so that the conductive material is removed from along the bottom and the first side during the anisotropically etching of the conductive material while leaving conductive material along the second side thereby forming a conductive strip.

18. The method of claim 16, wherein:

the recess forming step comprises forming a generally rectangular recess having first, second, third and fourth sides with the first and third sides being opposite one another and being downwardly and inwardly sloped sides oriented at acute angles to the upper surface; and the conductive strips forming step comprises forming the conductive strips as sidewall spacers at the second and fourth sides but not at the first or third sides.

19. The method of claim 14, wherein:

the conductive strips forming step comprises forming the conductive strips as sidewall spacers on sides of the second upward extensions but not on sides of the first upward extensions.

13

20. The method of claim **14**, further comprising forming interlayer conductors contacting upper surfaces of the conductive strips, the upper surfaces defining landing areas for the interlayer conductors.

21. The method of claim **20**, wherein the landing areas 5 extend along a landing area plane generally parallel to the upper surface or at an acute angle to the upper surface.

22. The method of claim **14**, further comprising forming interlayer conductors contacting landing areas created by upper ends of the conductive strips and adjacent ones of the 10 second upward extensions.

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14